24-Stage Frequency Divider

The MC14521B consists of a chain of 24 flip–flops with an input circuit that allows three modes of operation. The input will function as a crystal oscillator, an RC oscillator, or as an input buffer for an external oscillator. Each flip–flop divides the frequency of the previous flip–flop by two, consequently this part will count up to $2^{24} = 16,777,216$. The count advances on the negative going edge of the clock. The outputs of the last seven–stages are available for added flexibility.

Features

- All Stages are Resettable
- Reset Disables the RC Oscillator for Low Standby Power Drain
- RC and Crystal Oscillator Outputs Are Capable of Driving External Loads
- Test Mode to Reduce Test Time
- V_{DD}' and V_{SS}' Pins Brought Out on Crystal Oscillator Inverter to Allow the Connection of External Resistors for Low–Power Operation
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load over the Rated Temperature Range
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- This Device is Pb-Free and is RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

	007		
Parameter	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V _{in} , V _{out}	-0.5 to V _{DD} +0.5	V
Input or Output Current (DC or Transient) per Pin	I _{in} , I _{out}	±10	mA
Power Dissipation, per Package (Note 1)	P _D	500	mW
Ambient Temperature Range	T _A	-55 to +125	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C
Lead Temperature (8–Second Soldering)	TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: "D/DW" Package: –7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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SOIC-16 D SUFFIX CASE 751B

PIN ASSIGNMENT

Q24	þ	1●	16	þ	V_{DD}
RESET	þ	2	15	þ	Q23
$V_{SS}4$	þ	3	14	þ	Q22
OUT 2	þ	4	13	þ	Q21
$V_{DD}4$	þ	5	12	þ	Q20
IN 2	þ	6	11	þ	Q19
OUT1	þ	7	10	þ	Q18
V_{SS}	þ	8	9	þ	IN 1

MARKING DIAGRAMS



A = Assembly Location

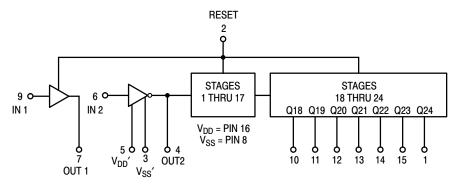
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week

ORDERING INFORMATION

= Pb-Free Package

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

BLOCK DIAGRAM



Output	Count Capacity
Q18	$2^{18} = 262,144$
Q19	$2^{19} = 524,288$
Q20	$2^{20} = 1,048,576$
Q21	$2^{21} = 2,097,152$
Q22	$2^{22} = 4,194,304$
Q23	$2^{23} = 8,388,608$
Q24	$2^{24} = 16,777,216$

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14521BDG	SOIC-16 (Pb-Free)	48 Units / Rail
NLV14521BDG*	SOIC-16 (Pb-Free)	48 Units / Rail
MC14521BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NLV14521BDR2G*	SOIC-16 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			- 5	5°C		25°C		125	5°C	
Characteristic	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage "0" Level $V_{in} = V_{DD}$ or 0	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD}	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" Level (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
"1" Level $(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
	Іон	5.0 10 15	-0.25 -0.62 -1.8	_ _ _	-0.2 -0.5 -1.5	-0.36 -0.9 -3.5	_ _ _	-0.14 -0.35 -1.1	_ _ _	mAdc
		5.0 5.0 10 15	-3.0 -0.64 -1.6 -4.2	- - - -	-2.4 -0.51 -1.3 -3.4	-4.2 -0.88 -2.25 -8.8	- - - -	-1.7 -0.36 -0.9 -2.4	- - - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	I _{in}	15	_	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current (Note 3, 4) (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	Ι _Τ	5.0 10 15	$I_{T} = (0.42 \mu\text{A/kHz}) \text{f} + I_{DD}$ $I_{T} = (0.85 \mu\text{A/kHz}) \text{f} + I_{DD}$ $I_{T} = (1.40 \mu\text{A/kHz}) \text{f} + I_{DD}$					μAdc		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
 Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF: I_T(C_L) = I_T(50 pF) + (C_L – 50) Vfk where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.003.

SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time (Counter Outputs) $t_{TLH},t_{THL}=(1.5\;\text{ns/pF})\;C_L+25\;\text{ns}\\ t_{TLH},t_{THL}=(0.75\;\text{ns/pF})\;C_L+12.5\;\text{ns}\\ t_{TLH},t_{THL}=(0.55\;\text{ns/pF})\;C_L+12.5\;\text{ns}$	t _{TLH} , t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q18 tpHL, tpLH = (1.7 ns/pF) C _L + 4415 ns tpHL, tpLH = (0.66 ns/pF) C _L + 1667 ns tpHL, tpLH = (0.5 ns/pF) C _L + 1275 ns Clock to Q24	t _{PHL} , t _{PLH}	5.0 10 15	- - -	4.5 1.7 1.3	9.0 3.5 2.7	μs
tock to Q24 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 5915 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 2167 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 1675 \text{ ns}$		5.0 10 15	- - -	6.0 2.2 1.7	12 4.5 3.5	
Propagation Delay Time Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) \text{ C}_L + 1215 \text{ ns}$ $t_{PHL} = (0.66 \text{ ns/pF}) \text{ C}_L + 467 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) \text{ C}_L + 350 \text{ ns}$	t _{PHL}	5.0 10 15	- - -	1300 500 375	2600 1000 750	ns
Clock Pulse Width	t _{WH(cl)}	5.0 10 15	385 150 120	140 55 40	- - -	ns
Clock Pulse Frequency	f _{cl}	5.0 10 15	- - -	3.5 9.0 12	2.0 5.0 6.5	MHz
Clock Rise and Fall Time	t _{TLH} , t _{THL}	5.0 10 15	- - -	- - -	15 5.0 4.0	μs
Reset Pulse Width	t _{WH(R)}	5.0 10 15	1400 600 450	700 300 225	- - -	ns
Reset Removal Time	t _{rem}	5.0 10 15	30 0 - 40	-200 -160 -110	- -	ns

- 5. The formulas given are for the typical characteristics only at 25°C.
 6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

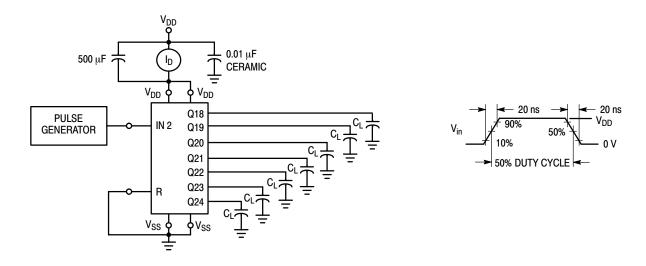


Figure 1. Power Dissipation Test Circuit and Waveform

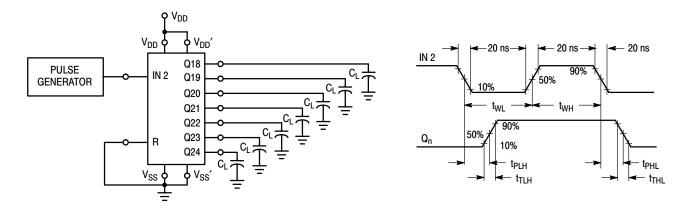
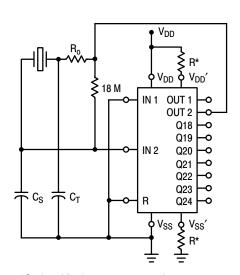


Figure 2. Switching Time Test Circuit and Waveforms



^{*}Optional for low power operation, 10 k Ω \leq R \leq 70 k Ω .

Figure 3. Crystal Oscillator Circuit

Characteristic	500 kHz Circuit	50 kHz Circuit	Unit
Crystal Characteristics Resonant Frequency Equivalent Resistance, R _S	500 1.0	50 6.2	kHz kΩ
External Resistor/Capacitor Values R ₀ C _T C _S	47	750	kΩ
	82	82	pF
	20	20	pF
Frequency Stability Frequency Change as a Function of V _{DD} (T _A = 25°C) V _{DD} Change from 5.0 V to 10 V V _{DD} Change from 10 V to 15 V	+ 6.0	+ 2.0	ppm
	+ 2.0	+ 2.0	ppm
Frequency Change as a Function of Temperature (V _{DD} = 10 V) T _A Change from – 55°C to + 25°C MC14521 only Complete Oscillator*	- 4.0	- 2.0	ppm
	+ 100	+ 120	ppm
T _A Change from +25°C to+125°C MC14521 only Complete Oscillator*	- 2.0 - 160	- 2.0 - 560	ppm ppm

^{*}Complete oscillator includes crystal, capacitors, and resistors.

Figure 4. Typical Data for Crystal Oscillator Circuit

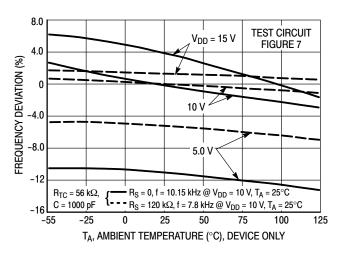
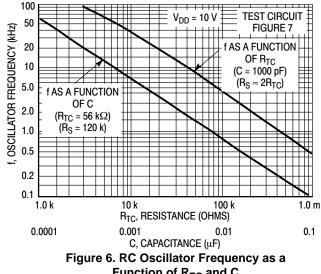


Figure 5. RC Oscillator Stability



Function of R_{TC} and C

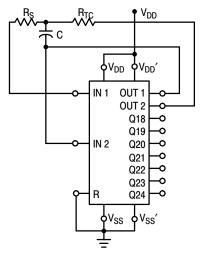


Figure 7. RC Oscillator Circuit

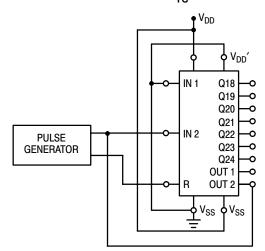
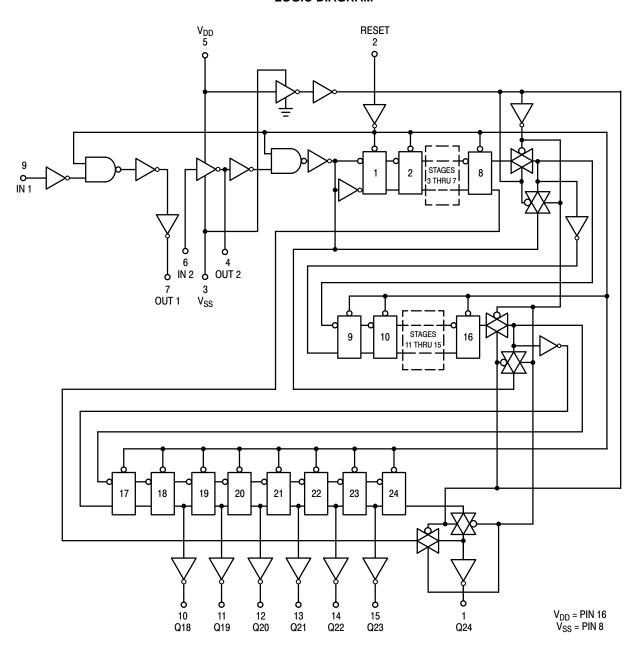


Figure 8. Functional Test Circuit

FUNCTIONAL TEST SEQUENCE

	Inpu	ıts	Outputs				Comments
	Reset	In 2	Out 2	V _{SS} ′	V _{DD} ′	Q18 thru Q24	Counter is in three 8–stage sections in parallel mode Counter is reset. In 2 and Out 2 are connected together.
	1	0	0	V_{DD}	GND	0	
A test function (see Figure 8) has been included for the reduction of test time required to exercise all 24 counter stages. This test function divides the counter into three 8–stage sections, and 255 counts are loaded in each of the 8–stage sections in parallel. All flip–flops are now at a logic "1". The counter is now returned to the normal 24–stages in	0	1	1				First "0" to "1" transition on In 2, Out 2 node.
		0 1 - -	0 1 - -				255 "0" to "1" transitions are clocked into this In 2, Out 2 node.
series configuration. One more pulse is entered into Input 2 (In 2) which will cause the counter to ripple		1	1			1	The 255th "0" to "1" transition.
from an all "1" state to an all "0" state.		0	0	•		1	
		1	0	GND	▼ V _{DD}	1	Counter converted back to 24–stages in series mode.
		1	0			1	Out 2 converts back to an output.
	V	0	1	V	V	0	Counter ripples from an all "1" state to an all "0" stage.

LOGIC DIAGRAM





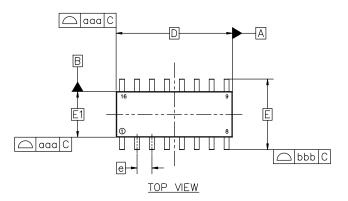


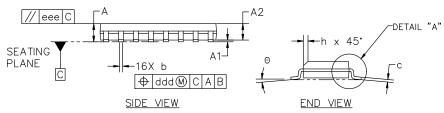
SOIC-16 9.90x3.90x1.50 1.27P CASE 751B ISSUE L

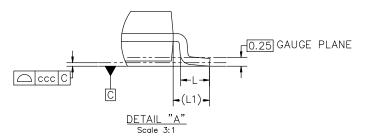
DATE 29 MAY 2024

NOTES:

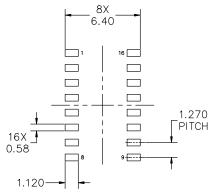
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
- 3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
- 5. DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE 6 DIMENSION AT MAXIMUM MATERIAL CONDITION.







MILLIMETERS							
DIM	MIN	MAX					
А	1.35	1.55	1.75				
A1	0.00	0.05	0.10				
A2	1.35	1.50	1.65				
b	0.35	0.42	0.49				
С	0.19	0.22	0.25				
D		9.90 BSC					
Е		6.00 BSC					
E1	3.90 BSC						
е	1.27 BSC						
h	0.25		0.50				
L	0.40	0.83	1.25				
L1		1.05 REF					
Θ	0.		7°				
TOLERAN	CE OF FO	ORM AND	POSITION				
aaa	0.10						
bbb	0.20						
ссс		0.10					
ddd		0.25	· · ·				
eee		0.10					



RECOMMENDED MOUNTING FOOTPRINT

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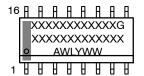
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SOIC-16 9.90x3.90x1.50 1.27P

CASE 751B ISSUE L

DATE 29 MAY 2024

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code A = Assembly Location

WL = Wafer Lot
 Y = Year
 WW = Work Week
 G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:		STYLE 2:		STYLE 3:	S	TYLE 4:	
	COLLECTOR	PIN 1.	CATHODE	PIN 1.	COLLECTOR, DYE #1	PIN 1.	COLLECTOR, DYE #1
	BASE	2.	ANODE	2.	BASE. #1	2.	
3.	EMITTER	3.	NO CONNECTION	3.	EMITTER. #1	3.	
4.	NO CONNECTION	4.	CATHODE	4.	COLLECTOR, #1	4.	COLLECTOR, #2
5.	EMITTER	5.	CATHODE	5.	COLLECTOR, #2	5.	COLLECTOR, #3
6.	BASE	6.	NO CONNECTION	6.	BASE, #2	6.	COLLECTOR, #3
7.	COLLECTOR	7.	ANODE	7.	EMITTER, #2	7.	COLLECTOR, #4
8.	COLLECTOR	8.	CATHODE	8.	COLLECTOR, #2	8.	COLLECTOR, #4
9.	BASE	9.	CATHODE	9.	COLLECTOR, #3	9.	BASE, #4
10.	EMITTER	10.	ANODE	10.	BASE, #3	10.	EMITTER, #4
11.	NO CONNECTION	11.	NO CONNECTION	11.	EMITTER, #3	11.	
	EMITTER	12.	CATHODE	12.		12.	
13.	BASE	13.		13.	COLLECTOR, #4	13.	BASE, #2
14.	COLLECTOR	14.	NO CONNECTION	14.	BASE, #4	14.	
15.	EMITTER	15.	ANODE	15.	EMITTER, #4	15.	
16.	COLLECTOR	16.	CATHODE	16.	COLLECTOR, #4	16.	EMITTER, #1
STYLE 5:		STYLE 6:		STYLE 7:			
PIN 1.	DRAIN, DYE #1	PIN 1.	CATHODE	PIN 1.	SOURCE N-CH		
2.	DRAIN, #1	2.	CATHODE	2.	COMMON DRAIN (OUTPUT)		
3.	DRAIN, #2	3.	CATHODE	3.	COMMON DRAIN (OUTPUT)		
4.	DRAIN, #2	4.	CATHODE	4.	GATE P-CH		
5.	DRAIN, #3	5.		5.	COMMON DRAIN (OUTPUT)		
6.	DRAIN, #3	6.		6.	COMMON DRAIN (OUTPUT)		
7.	DRAIN, #4	7.	CATHODE	7.	COMMON DRAIN (OUTPUT)		
0							
8.	DRAIN, #4		CATHODE	8.	SOURCE P-CH		
	GATE, #4	9.	ANODE	9.	SOURCE P-CH		
9. 10.	GATE, #4 SOURCE, #4	9. 10.	ANODE ANODE	9. 10.	SOURCE P-CH COMMON DRAIN (OUTPUT)		
9. 10. 11.	GATE, #4 SOURCE, #4 GATE, #3	9. 10. 11.	ANODE ANODE ANODE	9. 10. 11.	SOURCE P-CH COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT)		
9. 10. 11. 12.	GATE, #4 SOURCE, #4 GATE, #3 SOURCE, #3	9. 10. 11. 12.	ANODE ANODE ANODE ANODE	9. 10. 11. 12.	SOURCE P-CH COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT)		
9. 10. 11. 12. 13.	GATE, #4 SOURCE, #4 GATE, #3 SOURCE, #3 GATE, #2	9. 10. 11. 12. 13.	ANODE ANODE ANODE ANODE ANODE	9. 10. 11. 12. 13.	SOURCE P-CH COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) GATE N-CH		
9. 10. 11. 12. 13. 14.	GATE, #4 SOURCE, #4 GATE, #3 SOURCE, #3 GATE, #2 SOURCE, #2	9. 10. 11. 12. 13. 14.	ANODE ANODE ANODE ANODE ANODE ANODE	9. 10. 11. 12. 13.	SOURCE P-CH COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) GATE N-CH COMMON DRAIN (OUTPUT)		
9. 10. 11. 12. 13. 14.	GATE, #4 SOURCE, #4 GATE, #3 SOURCE, #3 GATE, #2 SOURCE, #2 GATE, #1	9. 10. 11. 12. 13. 14.	ANODE ANODE ANODE ANODE ANODE ANODE ANODE	9. 10. 11. 12. 13. 14.	SOURCE P-CH COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) GATE N-CH COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT)		
9. 10. 11. 12. 13. 14.	GATE, #4 SOURCE, #4 GATE, #3 SOURCE, #3 GATE, #2 SOURCE, #2	9. 10. 11. 12. 13. 14.	ANODE ANODE ANODE ANODE ANODE ANODE	9. 10. 11. 12. 13.	SOURCE P-CH COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) COMMON DRAIN (OUTPUT) GATE N-CH COMMON DRAIN (OUTPUT)		

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